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PATENT APPLICATION  
CMoore

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In-re the Application of:

Kazutaka SHIBATA

Application No.: 09/588,628

Filed: June 7, 2000

For: SEMICONDUCTOR CHIP WITH EXTERNAL CONNECTING TERMINAL (AS AMENDED)

Attorney Docket No.: ROH-023

Confirmation No.: 8757

Examiner: N. Ha

Art Unit: 2814

**AMENDMENT 37 C.F.R. §1.111**

Commissioner for Patents  
Washington, DC 20231

Sir:

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FEB 25 2003  
TECHNOLOGY CENTER 2800

In response to the non-final Office Action dated August 20, 2002, the period for response being extended to February 20, 2003, by the Petition for Extension of Time filed herewith, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please cancel claim 3 without prejudice or disclaimer.

Please amend claims 1, 2, 7, 18 and 19 as set forth below in clean form. Additionally, in accordance with 37 CFR 1.121(c)(1)(ii), amended claim(s) is/are set forth in a marked-up version in the page(s) attached to this Amendment.

1. (Thrice Amended) A semiconductor device, comprising:
- a semiconductor chip having an active surface and an inactive surface which is a surface on an opposite side of the active surface;
  - protective resin covering a sidewall of the semiconductor chip and having a surface formed so as to be flush with <sup>the</sup> an inactive surface of the semiconductor chip;
  - a board on which the semiconductor chip is mounted; and
  - an external connecting terminal joined to a surface of the board that is facing away from the semiconductor chip, the external connecting terminal being electrically connected to the active surface of the semiconductor chip.

S<sup>1</sup>